



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Intel Corporation

Title:

COMPOSITE THERMAL INTERFACE DEVICES AND METHODS FOR
INTEGRATED CIRCUIT HEAT TRANSFER

Docket No.: 884.848US1

Serial No.: 10/608,405

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Examiner: Gregory Thompson

Group Art Unit: 2835

Customer No.: 21186

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Commissioner for Patents

Notice of Allowance Date:

Attn: MAIL STOP ISSUE FEE

August 8, 2005

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